

Title (en)

THERMOSETTING ADHESIVE SHEET WITH ELECTROCONDUCTIVE AND THERMOCONDUCTIVE PROPERTIES

Title (de)

THERMISCH AUSHÄRTENDES KLEBEBLATT MIT ELEKTROLEITFÄHIGEN UND THERMOLEITFÄHIGEN EIGENSCHAFTEN

Title (fr)

FEUILLE ADHESIVE THERMODURCISSABLE PRESENTANT DES PROPRIETES ELECTROCONDUCTRICES ET THERMOCONDUCTRICES

Publication

EP 1490904 A1 20041229 (EN)

Application

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Priority

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- US 0309907 W 20030401

Abstract (en)

[origin: WO03085733A1] A thermosetting adhesive sheet with electroconductive and thermoconductive properties, which comprises a thermosetting adhesive sheet composed of a thermosetting adhesive composition comprising an ethylene-glycidyl (meth)acrylate copolymer and a carboxyl group-containing rosin, where crosslinking is formed between the ethylene of the copolymer by electron beam radiation, and having at least one through-opening region formed at a prescribed location, and further including a low melting point solder placed within said through-opening region(s) formed at the prescribed location(s).

IPC 1-7

H01L 23/373

IPC 8 full level

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CPC (source: EP KR)

C08L 93/04 (2013.01 - KR); **C09J 7/29** (2017.12 - KR); **C09J 123/08** (2013.01 - KR); **C09J 163/00** (2013.01 - EP KR); **H01B 1/22** (2013.01 - EP KR); **H01L 23/3737** (2013.01 - EP KR); **C08L 93/04** (2013.01 - EP); **C08L 2666/26** (2013.01 - EP KR); **H01L 2224/48091** (2013.01 - EP KR); **H01L 2224/73265** (2013.01 - EP KR)

Citation (search report)

See references of WO 03085733A1

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